

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Previously presented) An assembly for mounting a semiconductor device to a carrier substrate, comprising:  
an alignment device with at least one receptacle formed therein configured to receive at least a portion of at least one semiconductor device in nonparallel orientation relative to a carrier substrate; and  
at least one semiconductor device assembly including a mounting element with a receptacle configured to receive at least a portion of the at least one semiconductor device.
2. (Previously presented) The assembly of claim 1, wherein the at least one semiconductor device includes at least one contact adjacent a single edge thereof.
3. (Previously presented) The assembly of claim 2, wherein the alignment device comprises at least one contact located so as to be aligned with the at least one contact of the at least one semiconductor device upon interconnection thereof with the alignment device.
4. (Previously presented) The assembly of claim 3, wherein, upon interconnection of the at least one semiconductor device with the alignment device, the at least one contact of the alignment device resiliently abuts the at least one contact of the at least one semiconductor device to establish an electrically conductive connection therebetween.
5. (Previously presented) The assembly of claim 2, wherein the at least one semiconductor device comprises a semiconductor die and the at least one contact comprises a bond pad of the semiconductor die.

6. (Previously presented) The assembly of claim 1, wherein the alignment device is configured to engage or to be engaged by the mounting element.

7. (Withdrawn) The assembly of claim 6, wherein the alignment device includes an actuator for adjusting the alignment device between an engagement state and a nonengagement state.

8. (Withdrawn) The assembly of claim 1, wherein the alignment device includes a plurality of interconnection receptacles formed therein.

9. (Previously presented) The assembly of claim 1, wherein the receptacle of the mounting element is configured to receive and secure an edge of the at least one semiconductor device.

10. (Previously presented) A user-upgradable semiconductor device assembly, comprising:  
at least one semiconductor device, at least a portion of the at least one semiconductor device being disposed in a receptacle of a mounting element; and  
an alignment device including at least one receptacle configured to receive at least an edge of the at least one semiconductor device with the at least one semiconductor device being oriented nonparallel to a carrier substrate.

11. (Previously presented) The user-upgradable semiconductor device assembly of claim 10, wherein the alignment device is configured to engage or to be engaged by the mounting element.

12. (Withdrawn) The user-upgradable semiconductor device assembly of claim 10, wherein the alignment device includes an actuator positionable between a mounting element-engagement state and a mounting element-nonengagement state.

13. (Withdrawn) The user-upgradable semiconductor device assembly of claim 12, wherein the mounting element-nonengagement state facilitates removal of the at least one semiconductor device from the at least one receptacle.

14. (Currently amended) A semiconductor device package, comprising:  
at least one semiconductor device including a plurality of contacts located proximate a single edge of thereof;  
a retainer including at least one receptacle configured to receive another edge of the at least one semiconductor device, with the at least one semiconductor device secured within the at least one receptacle of the retainer with an adhesive material; and  
at least one mounting element associated with the retainer and configured to secure the at least one semiconductor device to a carrier.

15. (Previously presented) The semiconductor device package of claim 14, further comprising an alignment device configured to be mounted to the carrier.

16. (Previously presented) The semiconductor device package of claim 15, wherein the alignment device is configured to engage or to be engaged by the at least one mounting element.

17. (Withdrawn) The semiconductor device package of claim 15, wherein the alignment device includes an actuator positionable between a mounting element-engagement state and a mounting element-nonengagement state.

18. (Withdrawn) The semiconductor device package of claim 17, wherein the mounting element-nonengagement state facilitates removal of the at least one semiconductor device from the alignment device.

19. (Previously presented) The semiconductor device package of claim 15, wherein the alignment device includes at least one receptacle configured to receive at least the single edge of the at least one semiconductor device.

20. (Previously presented) The semiconductor device package of claim 19, wherein a plurality of contacts are positioned within the at least one receptacle so as to facilitate electrical connection with corresponding contacts of the at least one semiconductor device.

21. (Previously presented) The semiconductor device package of claim 14, wherein the at least one semiconductor device comprises a semiconductor die and each of the plurality of contacts comprises a bond pad of the semiconductor die.

22. (Withdrawn) The semiconductor device package of claim 14, wherein at least one contact of the plurality of contacts is disposed on the single edge.

23. (Withdrawn) The semiconductor device package of claim 15, wherein the alignment device includes a plurality of interconnection receptacles formed therein.

24. (Canceled)